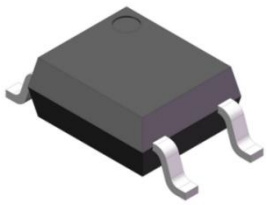
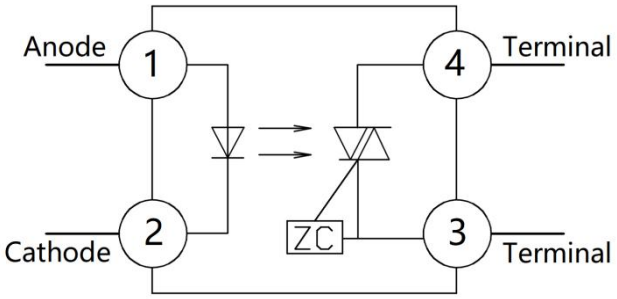
Product packaging logic diagram



SOP4



Pin Configuration

Features

- Peak breakdown voltage:
  250V：XLM303X；400V：XLM304X；
  600V：XLM306X；800V：XLM308X；
- High isolation voltage between input and output (Viso =3750V rms)
- Operating Temperature: -55℃~100℃
- Environmentally friendly products, compliant with CQC, UL, and VDE requirements

Mechanical Data

- Case: SOP4
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solder ability-per MIL-STD-202, Method 208

Applications

- Commonly used in motor speed control systems，Power regulation system and follow-up system，Control of high-power equipment through low-power controls.
- Mainly used for motor speed control and temperature control。
- In the power system for power switches，Charging pile control and battery management system（BMS）,Achieve precise control of voltage/current and equipment protection。
- Vehicle power management，Drive motor control and charge/discharge management，Improving vehicle energy efficiency and safety。
- In fiber optic communication equipment, routers and medical devices，signal isolation and power control in the middle，Ensure stable operation of equipment.



Ordering Information

XL	M30VX	(M)	(G)	-	(U)	(N)	(Y)
①	②	③	④		⑤	⑥	⑦

① Brand(XL)

② Product series(V:3,4,6,8 ; X:0,1,2,3,4)

③ Package type (SOP4:None)

④ Halogen option (None :Halogen free)

⑤ Lead frame (None: Copper)

⑥ Customer option 1 (0-9 or A-Z or none)

⑦ Customer option 2 (0-9 or A-Z or none)

Part Number	Package	Shipping Quantity	Marking Code
XLM30V*1X*2	SOP4	3000pcs / Tape & Reel	XLM30V*1X*2

Marking Information

- " XL" denotes brand
- " V" denotes VDRM digit: 3, 4, 6 ,8
- " X" denotes IFT digit: 0, 1, 2, 3, 4
- " Y" denotes Year : A(2024), B(2025), C(2026)
- " WW" denotes Week' s number
- " N" denotes the day of Week

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter			Symbol	Value	Unit
Input	Forward Current		I_F	60	mA
	Reverse Voltage		V_R	6	V
	Power Dissipation		P_D	100	mW
	Derating factor (above Ta = 85 ℃)			3.8	mW/°C
Output	Power Dissipation		P_C	300	mW
	Derating factor (above Ta = 85 ℃)			7.6	mW/°C
	Off-state Output Terminal Voltage	XLM303X	V_{DRM}	250	V
		XLM304X		400	
		XLM306X		600	
		XLM308X		800	
	Peak repetitive surge current (pw=100μs,120pps)		I_{TSM}	1	A
	Turn-on current (root mean square value)		$I_{T(RMS)}$	100	mA

Thermal Characteristics

Parameter	Symbol	Value	Unit
Total Power Dissipation	P_{TOT}	330	mW
Isolation Voltage *1	V_{ISO}	3750	Vrms
Operating Temperature	T_{OPR}	-55 ~ +110	°C
Storage Temperature Range	T_{STG}	-55 ~ +125	°C
Soldering Temperature *2	T_{SOL}	260	°C

Notes:

1. 40 to 60% RH, AC for 1 minute. At this time, pins 1, 2 & 3 are shorted, and pins 4, 5 & 6 are shorted together.
2. For 10 seconds

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Parameter			Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage		V_F	I_F=20mA	-	1.23	1.5	V
	Reverse Leakage current		I_R	V_R=6V	-	-	10	μA
Output	Peak Blocking Current	XLM303X	I_{DRM}	V_{DRM} =Rated V_{DRM}, I_F= 0mA	-	-	100	nA
		XLM304X						
		XLM306X			-	-	500	
		XLM308X						
	Peak on-state voltage		V_{TM}	I_{TM}=100mA, I_F=Rated I_{FT}	-	-	3	V
	Critical Rate of Rise off-state Voltage	XLM303X	dv/dt	V_{PEAK} =Rated V_{DRM}, I_F= 0mA	1000	-	-	V/μs
		XLM304X						
		XLM306X						
		XLM308X			600	-	-	
	Inhibition voltage (MT1-MT2 voltage above which device will not trigger)		V_{Inh}	I_F= Rated I_{Ft}	-	-	20	V
	Leakage in Inhibited State		I_{DRM2}	I_F= Rated I_{Ft} V_{DRM} =Rated V_{DRM} off state	-	-	500	μA
Transfer Characteristics	LED trigger current	XLM3031	I_{FT}	Main terminal voltage = 3V	-	-	15	mA
		XLM3041						
		XLM3061						
		XLM3081						
		XLM3032			-	-	10	
		XLM3042						
		XLM3062						
		XLM3082						
		XLM3033			-	-	5	
		XLM3043						
		XLM3063						
		XLM3083						
		XLM3034			-	-	3	
		XLM3044						
		XLM3064						
		XLM3084						
	Holding Current		I_H		-	250		μA

Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

Fig.1 LED Positive voltage vs Positive current

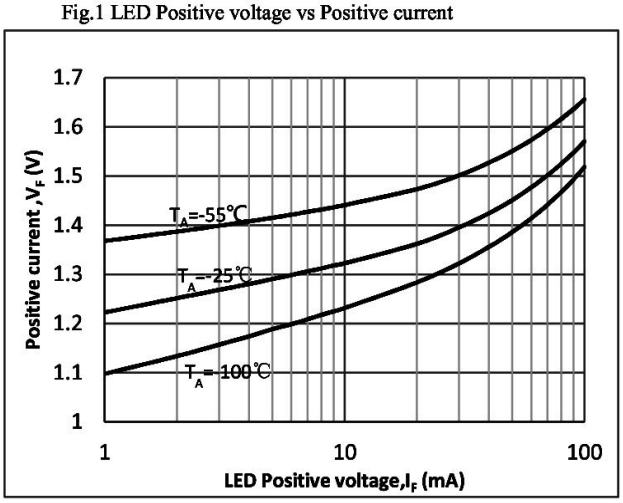


Fig.2 On-state characteristic

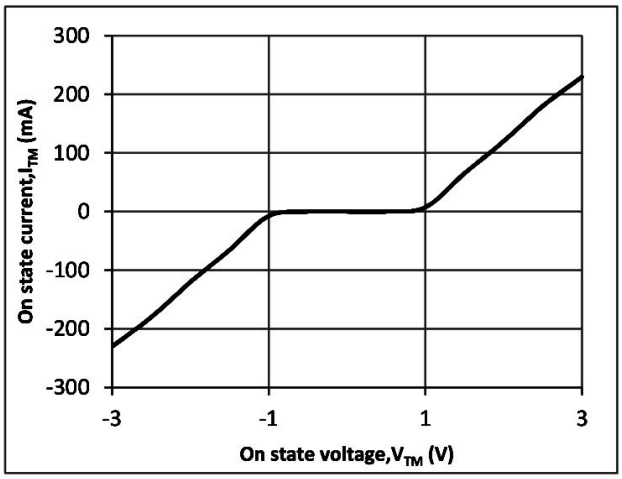


Fig.3 Trigger current vs Ambient temperature

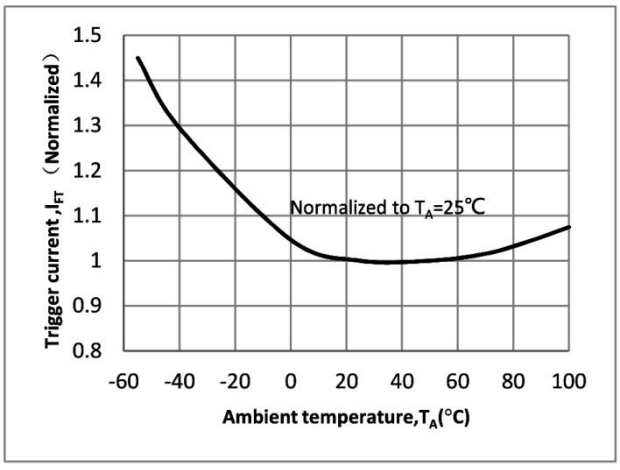


Fig4 LED Trigger current vs LED Pulse Width

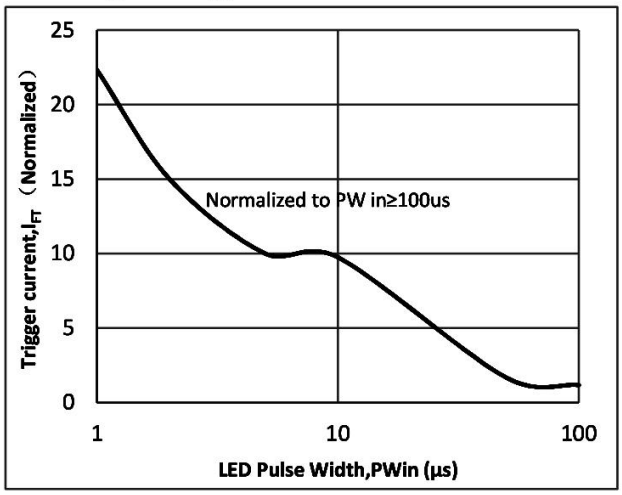


Fig.5 Holding current vs Temperature

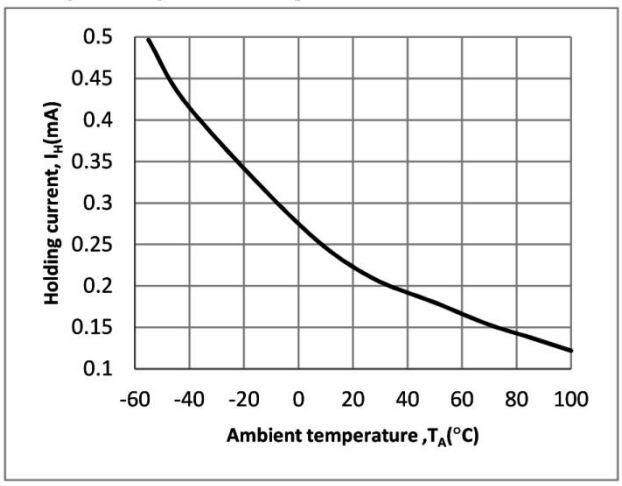
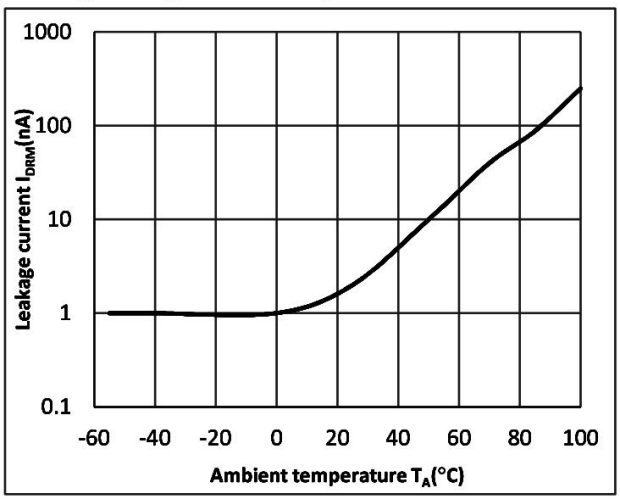


Fig.6 Leakage current vs Temperature



Ratings and Characteristics Curves (@ T_A = 25°C unless otherwise specified)

Fig.7 Inhibit state leakage current vs Ambient temperature

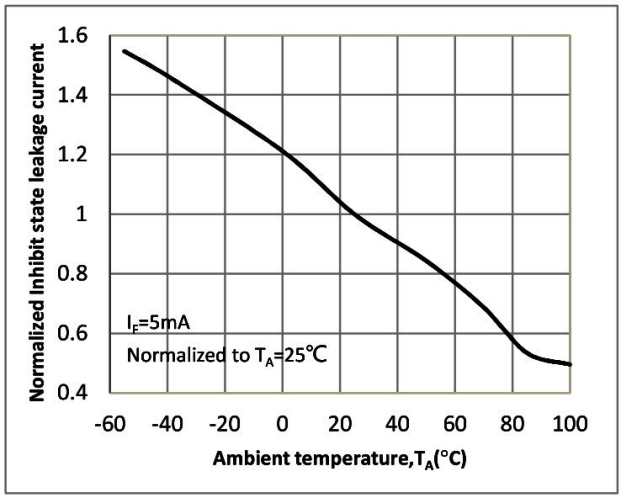


Fig.8 Inhibition voltage vs Ambient temperature

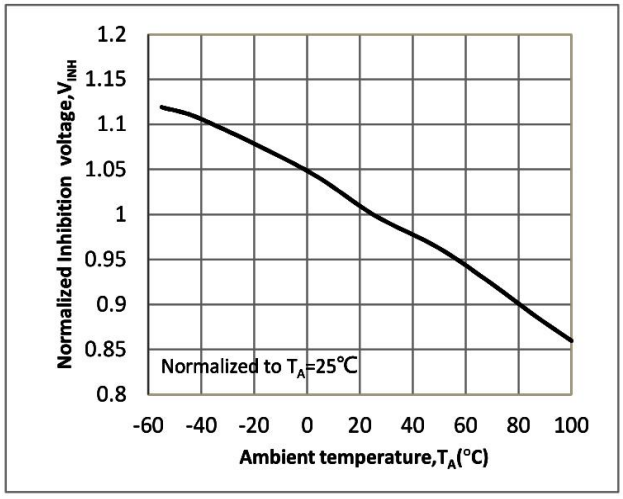
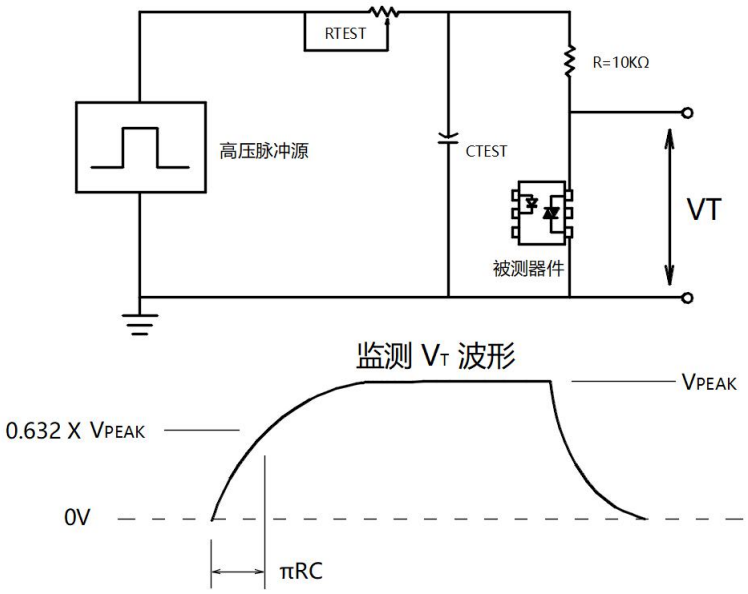


Fig.9 Static dv / dt test circuit and waveform



The high voltage pulse applied to the output of the device under test through the RC circuit is set to the required VPEAK value. LED current is not applied. The waveform VT is monitored with X100 probe.

By adjusting the RTEST value, the dv/dt (slope) increases until the device under test is observed to be triggered (waveform collapse).Then dv/dt drops until the device under test stops being triggered. At this point, RC is recorded and the dv/dt calculated.

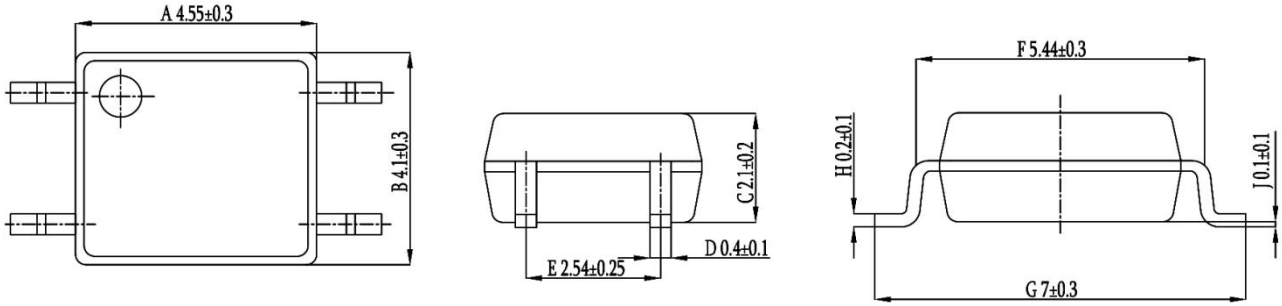
$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

For example, VPEAK = 400V for BL52X series. The dv/dt value is calculated as follows:

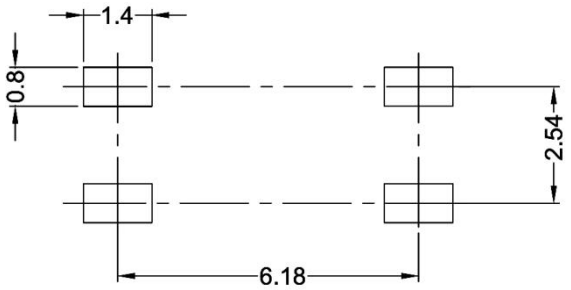
$$dv/dt = \frac{0.632 \times 400}{\tau_{RC}} = \frac{252}{\tau_{RC}}$$

Package Outline Dimensions (unit: mm)

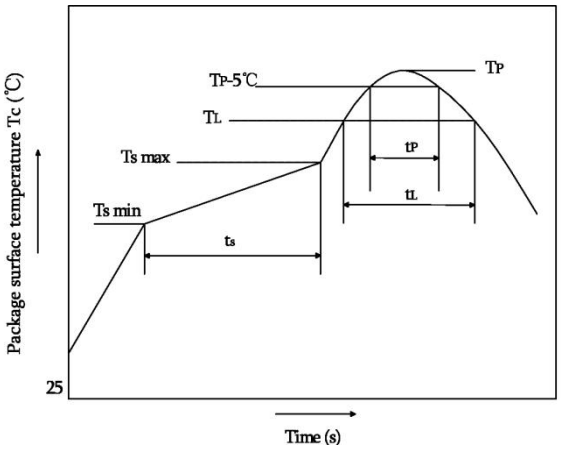
SOP4



SOLDERING FOOTPRINT (unit: mm)



Reflow soldering

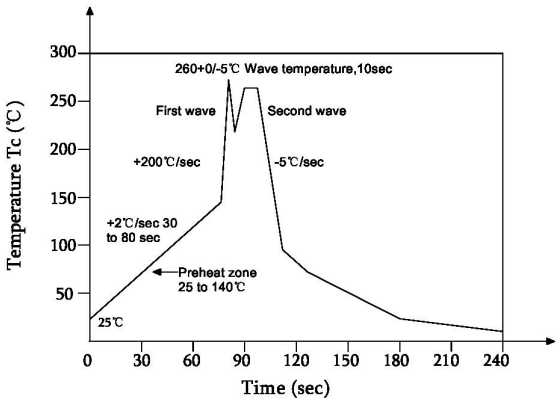


	Symbol	Min	Max	Unit
Preheat temperayure	Ts	150	200	℃
Preheat time	ts	60	120	s
Ramp-up ratea(T_L to T_P)			3	℃/s
Liquidus temperature	T_L	217		℃
Time above T_L	t_L	60	150	s
Peak temperature	Tp		260	℃
Time during which Tc is between (T_P-5) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	℃/s

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering



Profile feature	
Average ramp-up rate	~200℃/s
Heating rate during preheat	1℃/s to 2℃/s typical;4℃/s maximum
Final preheat temperature Ts	~130℃
Preheat time (25℃ to Ts)	>60s
Peak temperature Tp	260℃
Time within peak temperature tp	10s
Ramp-down rate	5℃/s maximum

Soldering with hand soldering iron

A. Hand soldering iron is only used for product rework or sample testing.

B. Hand soldering iron requirements:Temperature:360 ℃+5℃ within 3s.

Packing

Package Type	Packing Form	Quantity per Tube &Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
SOP4	Reel(ϕ330mm)	3000pcs/reel	2 reels /box	5 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Leave 20 Spaces at the beginning and 50 Spaces at the end

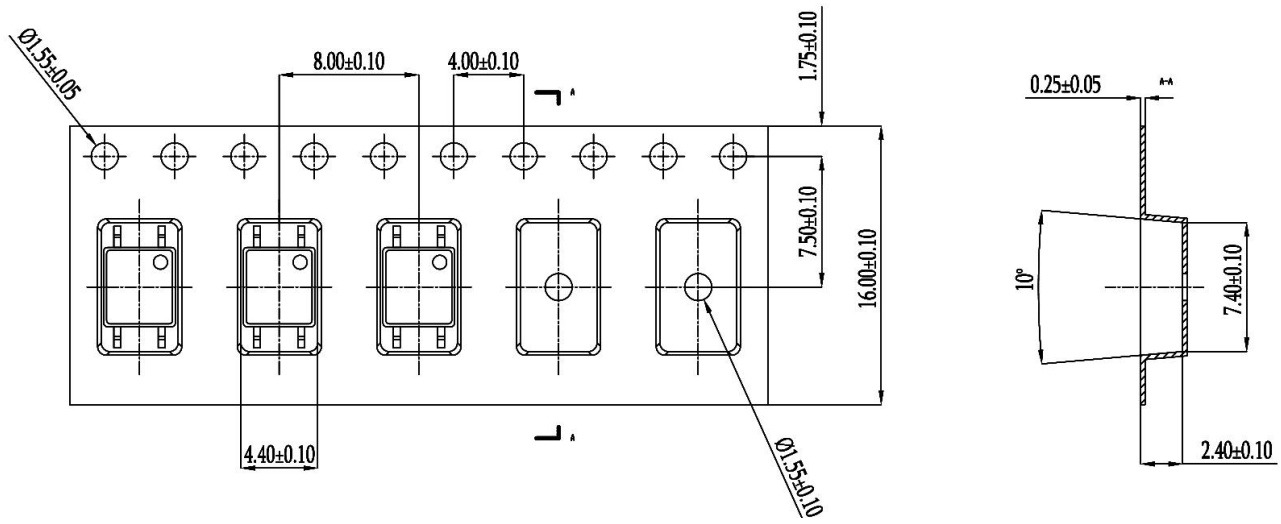
■ Summary table

■ SOP4 (Reel)

Qty/reel: 3000pcs. Qty/box: 6000pcs.

Qty/ctn : 30000pcs.

Schematic: (unit:mm)



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